

INFORMATION DISCLOSURE CITATION
(Use several sheets if necessary)

Docket Number (Optional)
BUR920030025US1

Application Number
10/605,440

Applicant(s)
Robert Geffken et al.

Filing Date
09/30/2003

Group Art Unit
Unknown 2818

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

<i>dh</i>		V. Arnal, J. Torres, P. Gayet, R. Gonella, P. Spinelli, M. Guillermet, J-P Reynard, GC. Verove; "Integration of a 3 Level CuSiO2 Air Gap Interconnect for Sub 0.1 micron DMOS Technologies;" IEEE, 6/01, pages 298-300.

EXAMINER *Thaw*

DATE CONSIDERED **10/02/05**

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention

ADJUSTABLE SELF-ALIGNED AIR GAP DIELECTRIC FOR
LOW CAPACITANCE WIRING

Application Number :

10/605,440

Confirmation Number:

First Named Applicant:

Robert Geffken

Attorney Docket Number:

BUR920030025US1

Art Unit:

2818

Examiner:

Das H. Nguyen

Search string:

(5324683 or 6150232 or 6200900 or 6281585 or 6329279 or 6423629 or 6472266
or 20020127844 or 20010023123).pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
dh	1	5324683	1994-06-28	Fitch et al.		437	65
	2	6150232	2000-11-21	Chan et al.		438	421
	3	6200900	2001-03-13	Kitch		438	695
	4	6281585	2001-08-28	Bothra		257	758
	5	6329279	2001-12-11	Lee		438	619
	6	6423629	2002-07-23	Ahn et al.		438	622
dh	7	6472266	2002-10-29	Yu et al.		438	241

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
dh	1	20020127844	2002-09-12	Grill et al.		438	622
dh	2	20010023123	2001-09-20	Kim		438	587

Signature

Examiner Name

Das H. Nguyen

Date

10/02/2005